

	Type	Search Text	DBs	Time Stamp
1	BRS	174/255	USPAT	2003/12/23 06:42
2	BRS	174/255	US-P GPU B; EPO; JPO; DER WEN T; IBM_ TDP	2003/12/23 06:43
3	BRS	174/258	USPAT; US-P GPU B; EPO; JPO; DER WEN T; IBM_ TDP	2003/12/23 06:54
4	BRS	174/262	USPAT; US-P GPU B; EPO; JPO; DER WEN T; IBM_ TDP	2003/12/23 07:12

	Type	Search Text	DBs	Time Stamp
5	BRS	174/264	USPA T; US-P GPU B; EPO; JPO; DER WEN T; IBM_ TDP	2003/12/23 07:20
6	BRS	174/266	USPA T; US-P GPU B; EPO; JPO; DER WEN T; IBM_ TDP	2003/12/23 07:29
7	BRS	361/795	USPA T; US-P GPU B; EPO; JPO; DER WEN T; IBM_ TDP	2003/12/23 07:36

	Type	Search Text	DBs	Time Stamp
8	BRS	(361/792 or 361/761) and modulus	USPAT; US-P GPU B; EPO; JPO; DER WEN T; IBM_ TDP	2003/12/23 07:39
9	BRS	361/762	USPAT; US-P GPU B; EPO; JPO; DER WEN T; IBM_ TDP	2003/12/23 07:57
10	BRS	361/764	USPAT; US-P GPU B; EPO; JPO; DER WEN T; IBM_ TDP	2003/12/23 07:57

	Type	Search Text	DBs	Time Stamp
11	BRS	(257/724 or 257/687 or 257/690 or 257/788 or 257/795) and (semiconductor or chip or die or IC or active near components) and (inorganic near filler same thermosetting near resin) and (via or opening or open)	USPAT	2003/12/23 08:43
12	BRS	(257/724 or 257/687 or 257/690 or 257/788 or 257/795) and (semiconductor or chip or die or IC or active near components) and (inorganic near filler same thermosetting near resin) and (via or opening or open)	USPAT; US-PGPU B; EPO; JPO; DERWENT; IBM_TDP	2003/12/23 08:44
13	BRS	(361/760 or 361/782 or 310/340 or 310/313 or 264/272.11) and (semiconductor or chip or die or IC or active near components) and (inorganic near filler same thermosetting near resin) and (via or opening or open)	USPAT; US-PGPU B; EPO; JPO; DERWENT; IBM_TDP	2003/12/23 08:45